

	COUNT	DESCRIPTION OF REVISIONS	BY	CHKD	DATE		COUNT	DESCRIPTION OF REVISIONS	BY	CHKD	DATE				
△						△									
△						△									
APPLICABLE STANDARD															
RATING	Operating Temperature Range		-55°C to 105°C (Note1)			Storage Temperature Range		-10°C to +60°C (Note3)							
	Operating Humidity Range		20% to 80% (Note2)			Storage Humidity Range		40% to 70% (Note3)							
	Applicable Connector		DF51K-10DS-2C(###)			Current		AWG 30 : 0.5A AWG 28 : 1A							
	Voltage		250V AC/DC					AWG 26 : 1.5A AWG 22-24 : 2A							
SPECIFICATIONS															
ITEM		TEST METHOD				REQUIREMENTS			QT	AT					
CONSTRUCTION															
General Examination		Visually and by measuring instrument.				According to drawing.			O	O					
Marking		Confirmed visually.							O	O					
ELECTRICAL CHARACTERISTICS															
Contact Resistance		20mV MAX, 1mA (DC or 1000Hz).				30 mΩ MAX.			O	-					
Millivolt Level Method															
Insulation Resistance		500 V DC.				1,000 MΩ MIN.			O	-					
Voltage Proof		650 V AC for 1 min.				No flashover or breakdown.			O	-					
MECHANICAL CHARACTERISTICS															
Mechanical Operation (Sn Plating)		30 times insertion and extraction.				①Contact resistance: 30mΩ MAX ②No damage, crack or looseness of parts.			O	-					
Mechanical Operation (Au Plating)		50 times insertion and extraction.				①Contact resistance: 30mΩ MAX ②No damage, crack or looseness of parts.			O	-					
Mating and unmating force (Sn Plating)		It takes out and inserts with a conformity connector.				①Insertion Force: 48.2N MAX ②Extraction Force: 2.7N MIN			O	-					
Mating and unmating force (Au Plating)		It takes out and inserts with a conformity connector.				①Insertion Force: 31.2N MAX ②Extraction Force: 2.5N MIN			O	-					
Vibration		Frequency 10 to 55 Hz, single amplitude 0.75 mm, at 10 cycles for 3 direction.				①No electrical discontinuity of 1 μ s. ②No damage, crack or looseness of parts.			O	-					
Shock		Acceleration 490 m/s ² duration of pulse 11 ms at 3 times for 3 directions.							O	-					
ENVIRONMENTAL CHARACTERISTICS															
Damp Heat (Steady State)		Exposed at 40 ± 2 °C , humidity 90 to 95 %, 96 h. (After leaving the room temperature for 1 to 2h.)				①Contact resistance: 30 mΩ MAX. ②Insulation resistance: 500MΩ MIN. ③No damage, crack or looseness of parts.			O	-					
Remarks Note 1: Include the temperature rising by current. Note 2: No condensing Note 3: Apply to the condition of long term storage for unused products before pcb on board, after pcb board , operating temperature and humidity range is applied for interim storage during transportation.															
					DRAWN J.S CHOI 17.12.22	DESIGNED J.S CHOI 17.12.22	CHECKED S.M.LIM 17.12.22	APPROVED T.S KANG 17.12.22	RELEASED ENG 20.02.13 DEPT						
Unless otherwise specified, refer to IEC 60512.															
NOTE QT: QUALIFICATION TEST AT: ASSURANCE TEST O: APPLICABLE TEST															
HIROSE KOREA CO.,LTD.				SPECIFICATION SHEET			PART NO. DF51K-10DP-2DSA(800)								
CODE NO.(OLD) CL			DRAWING NO. ELC4-632460			CODE NO. CL 6652-0009-3-800					1 2				

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In case of consideration for using Automotive equipment / device which demand high reliability, kindly contact our sales window correspondents.

Rapid Change of Temperature	Temperature -55 °C → +105 °C Time 30min → 30min Under 5 Cycles. (The transferring time of the tank is 2 to 3 MIN) (After leaving the room temperature for 1 to 2h.)	①Contact resistance: 30 mΩ MAX. ②Insulation resistance: 1,000MΩ MIN. ③No damage, crack or looseness of parts.	O	—
Dry Heat	Exposed at 105±2 °C, 96h	①Contact resistance: 30 mΩ MAX. ②Insulation resistance: 1,000MΩ MIN. ③No damage, crack or looseness of parts.	O	—
Cold	Exposed at -55±3 °C, 96h	①Contact resistance: 30 mΩ MAX. ②Insulation resistance: 1,000MΩ MIN. ③No damage, crack or looseness of parts.	O	—
Resistance To Soldering Heat	①Automatic soldering (flow) Soldered at solder temperature, 260 °C for in immersion , duration, 5 s. ②Manual soldering Soldering iron temperature :270 °C, Soldering time :3s. No strength on contact.	No deformation of case of excessive looseness of the terminals.	O	—
Solderability	Soldering temperature: 245 °C Duration of immersion :soldering, for 5 sec.	New uniform coating of solder shall cover minimum of 95 % of the surface Being immersed.	O	—

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